WHAT IS CLAIMED IS:

1. A storage medium comprising:

an information recording surface for recording information; and

an electronic-circuit mounting surface where electronic circuits are mounted at least on one portion.

2. The storage medium according to claim 1, wherein said storage medium has a front surface and a rear surface,

and wherein said information recording surface is one of the front and rear surfaces, while said electronic-circuit mounting surface is the other one of the front and rear surfaces.

3. The storage medium according to claim 1, wherein said electronic circuits include an electronic device mounted on an insulating substrate including a printed circuit board and a ceramic substrate.

4. The storage medium according to claim 1, wherein said electronic circuits include a semiconductor circuit formed on a silicon wafer, a ceramic substrate or an insulating substrate.

5. The storage medium according to claim 1, wherein

said electronic circuits have a layered structure.

6. The storage medium according to claim 1, wherein said electronic circuits have communication means for communicating with outside.

7. The storage medium according to claim 6, wherein said communication means includes a contact-type or non-contact type contact.

8. The storage medium according to claim 6, wherein said communication means transmits energy superimposed with a signal.

9. The storage medium according to claim 1, wherein said electronic circuit has power means for storing energy supplied from a battery which generates energy from inside, or from outside via a contact point, optical means, wireless means or induction.

10. The storage medium according to claim 1, wherein said storage medium includes a magnetic disk, an optical disk such as a CD or a DVD, a magneto-optical disk such as an MO, an optical card, or a magneto-optical card.

11. A method for manufacturing a storage medium where

electronic circuits are mounted, comprising:

a step of manufacturing an information recording surface for recording information;

a step of manufacturing an electronic-circuit mounting surface including said electronic circuits at least on one portion; and

a step of attaching said information recording surface to said electronic-circuit mounting surface.

12. The method for manufacturing a storage medium where electronic circuits are mounted, comprising:

a step of manufacturing an information recording surface for recording information; and

a step of forming an electronic-circuit mounting surface including said electronic circuits at least on one portion, on the rear surface of said information recording surface.

13. A method for manufacturing a storage medium where electronic circuits are mounted, comprising:

a step of manufacturing an electronic-circuit mounting surface including said electronic circuits at least on one portion; and

a step of forming an information recording surface for recording information, on the rear surface of said electronic-circuit mounting surface.

14. The method according to claim 11, wherein said step of manufacturing said information recording surface includes:

a step of injecting a base;

a step of forming a reflection film on said base; and

a step of coating said reflection film with a protective film.

15. The method according to claim 11, wherein said step of manufacturing said electronic-circuit mounting surface includes;

a step of mounting the electronic circuit; and

a step of coating or forming a protective film or layer over said electronic circuit.

16. The method according to claim 15, wherein said step of mounting said electronic circuit includes:

a step of forming a conductive wiring:

a step of mounting an insulating substrate including a printed circuit board and a ceramic substrate, where an electronic device is mounted, or a silicon wafer, a ceramic substrate or an insulating substrate, where a semiconductor circuit is formed.

17. The method according to claim 15, wherein said step of mounting said electronic circuit includes;

a step of forming a silicon wafer, a ceramic substrate or an insulating substrate; and

a step of forming a semiconductor circuit on said silicon wafer, ceramic substrate or insulating substrate.

18. The method according to claim 12, wherein said step of manufacturing said information recording surface includes:

a step of injecting a base;

a step of forming a reflection film on said base; and

a step of coating said reflection film with a protective film.

19. The method according to claim 12, wherein said step of manufacturing said electronic-circuit mounting surface includes;

a step of mounting the electronic circuit; and

a step of coating or forming a protective film or layer over said electronic circuit.

20. The method according to claim 19, wherein said step of mounting said electronic circuit includes:

a step of forming a conductive wiring:

a step of mounting an insulating substrate including a printed circuit board and a ceramic substrate, where an electronic device is mounted, or a silicon wafer, a ceramic substrate or an insulating substrate, where a semiconductor circuit is formed.

21. The method according to claim 19, wherein said step of mounting said electronic circuit includes;

a step of forming a silicon wafer, a ceramic substrate or an insulating substrate; and

a step of forming a semiconductor circuit on said silicon wafer, ceramic substrate or insulating substrate.

22. The method according to claim 13, wherein said step of manufacturing said information recording surface includes:

a step of injecting a base;

a step of forming a reflection film on said base; and

a step of coating said reflection film with a protective film.

23. The method according to claim 13, wherein said step of manufacturing said electronic-circuit mounting surface includes;

a step of mounting the electronic circuit; and

a step of coating or forming a protective film or layer over said electronic circuit.

24. The method according to claim 23, wherein said step of mounting said electronic circuit includes:

a step of forming a conductive wiring:

a step of mounting an insulating substrate including a printed circuit board and a ceramic substrate, where an electronic device is mounted, or a silicon wafer, a ceramic substrate or an insulating substrate, where a semiconductor circuit is formed.

25. The method according to claim 23, wherein said step of mounting said electronic circuit includes;

a step of forming a silicon wafer, a ceramic substrate or an insulating substrate; and

a step of forming a semiconductor circuit on said silicon wafer, ceramic substrate or insulating substrate.

26. The method according to claim 11, wherein said storage medium includes a magnetic disk, a magnetic card, an optical disk such as a CD or a DVD, a magneto-optical disk such as an MO, an optical card or a magneto-optical card.